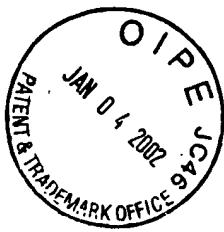


Exhibit

A

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Date Mailed: September 19, 2001 | By: AW/cle | PTO DATE STAMP:  
Serial No.: 09/872,796 | Docket No.: 50544.00004 (NVL 379)  
Applicant(s): Craig L. Stevens  
Title: ARCHITECTURE FOR HIGH THROUGHPUT SEMICONDUCTOR PROCESSING APPLICATIONS

The following has been received in the U.S. Patent Office on the date stamped hereon:

Patent Application \_\_\_\_ Pages \_\_\_\_ Claims       Amendment  
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 Assignment & Recordation Cover Sheet       Fee Transmittal for FY 2001 (in duplicate)  
 Verified Statement Claiming Small Entity Status       Appeal Brief (in triplicate)  
 Continued Prosecution Application (§1.53(d))       Issue Fee Transmittal (in duplicate)  
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